Docket No.: 006365 USA/MTCG/PCTRL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of

Yuri KOKOTOV et al.

Serial No. 10/712,273

Group Art Unit:

Filed: November 14, 2003

Examiner:

For: METHOD, SYSTEM AND MEDIUM FOR CONTROLLING MANUFACTURE PROCESS HAVING MULTIVARIATE INPUT PARAMETERS

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R.§ 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

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publication indicated for an item is taken from the face of the item, and Applicant reserves the

right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent

applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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Date: 6/16/04

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CITATIO APPLIC (PTO-	1449)	SURE	ATTY. DOCKET 006365 USA/MT APPLICANT Yuri KOKOT	rcg/pctrl	SERIAL No. 10/712,2		
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PATENT NO.	DATE		NAME	CLASS	SUBCLASS		
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)

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APPLICANT

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FILING DATE
November 14, 2003

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